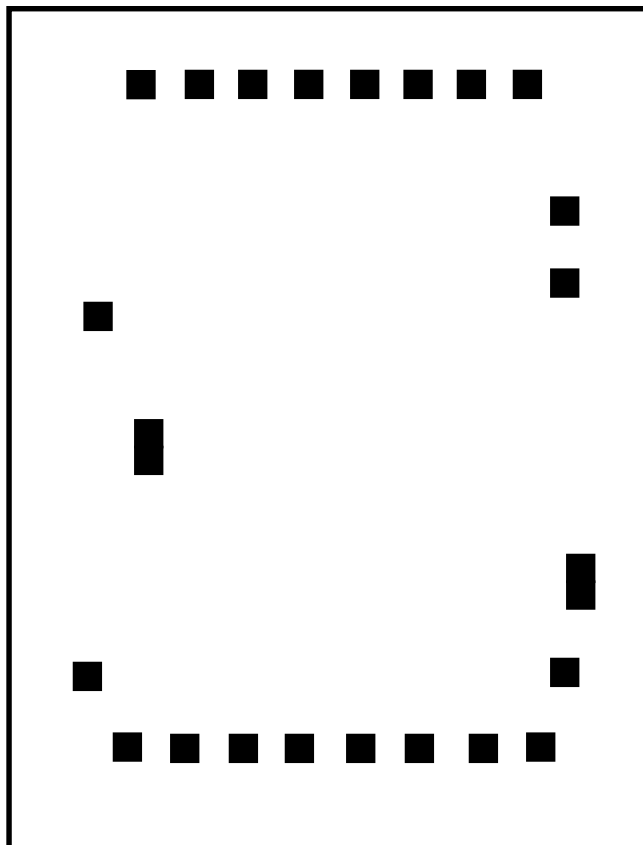


### HV513-6in Pad Function

1	D <sub>IN</sub>
2	HiZ
3	Short
4	$\overline{LE}$
5	CLK
6	SEL
7	POL
8	$\overline{BL}$
9	D <sub>OUT</sub>
10	V <sub>DD</sub>
11	V <sub>PP</sub>
12	V <sub>PP</sub>
13	HV <sub>OUT8</sub>
14	HV <sub>OUT8</sub>
15	HV <sub>OUT7</sub>
16	HV <sub>OUT6</sub>
17	HV <sub>OUT5</sub>
18	HV <sub>OUT4</sub>
19	HV <sub>OUT3</sub>
20	HV <sub>OUT2</sub>
21	HV <sub>OUT1</sub>
22	HV <sub>OUT1</sub>
23	HVGND
24	HVGND
25	LVGND

### HV514-6in Pad Function

1	D <sub>IN</sub>
2	nc
3	nc
4	$\overline{LE}$
5	CLK
6	SEL
7	nc
8	$\overline{BL}$
9	D <sub>OUT</sub>
10	V <sub>DD</sub>
11	V <sub>PP</sub>
12	V <sub>PP</sub>
13	HV <sub>OUT8</sub>
14	HV <sub>OUT8</sub>
15	HV <sub>OUT7</sub>
16	HV <sub>OUT6</sub>
17	HV <sub>OUT5</sub>
18	HV <sub>OUT4</sub>
19	HV <sub>OUT3</sub>
20	HV <sub>OUT2</sub>
21	HV <sub>OUT1</sub>
22	HV <sub>OUT1</sub>
23	HVGND
24	HVGND
25	LVGND



### Pad Coordinates in Microns

1	0; 0
2	250; 0
3	499.5; 0
4	749.5; 0
5	999; 0
6	1248.5; 0
7	1498; 0
8	1855; 0
9	1860; -676.5
10	1860; -1034.5
11	1907; -1911.5
12	1907; -2011.5
13	1865; -2171.5
14	1663; -2437
15	1448; -2437
16	1233; -2437
17	1018; -2437
18	803; -2437
19	588; -2437
20	373; -2437
21	158; -2437
22	-84; -2277
23	-36; -1836
24	-36; -1736
25	-24.5; -1005

## Die Specifications

	mils	mm		
<b>Die Size:</b>	91 x 133.8	2.31 x 3.400	<b>Back Side Metal:</b>	None
<b>Die Thickness:</b>	20 ±1	0.50 ±0.02	<b>Back Side Potential:</b>	V <sub>PP</sub>
<b>Bond Pad Size:</b>	4 x 4	0.10 x 0.10	<b>Die Attach Material:</b>	Epoxy Ablestick 84-1 LMIS
<b>Bond Wire Size:</b>	1.3	0.03	<b>Bond Pad Metal:</b>	Al/Si/Cu